

L Number	Hits	Search Text	DB	Time stamp
-	226	(438/458).CCLS.	USPAT;	2002/03/06 11:21
-	446897	bond or bonding or bonded	US-PGPUB	2002/03/07 14:35
-	178	((438/458).CCLS.) and (bond or bonding or bonded)	USPAT;	2002/03/06 11:23
-	18697	delaminat\$	US-PGPUB	2002/03/07 14:35
-	16	((438/458).CCLS.) and (bond or bonding or bonded)) and delaminat\$	USPAT;	2002/03/06 11:31
-	234	438/406.ccls.	US-PGPUB	2002/03/06 11:31
-	189	(bond or bonding or bonded) and 438/406.ccls.	USPAT;	2002/03/06 11:31
-	8	delaminat\$ and ((bond or bonding or bonded) and 438/406.ccls.)	US-PGPUB	2002/03/06 11:33
-	39	438/506.ccls.	USPAT;	2002/03/06 11:34
-	1	delaminat\$ and 438/506.ccls.	US-PGPUB	2002/03/06 11:34
-	3	(bond or bonding or bonded) and 438/506.ccls.	USPAT;	2002/03/06 11:34
-	36	438/506.ccls. not ((bond or bonding or bonded) and 438/506.ccls.)	US-PGPUB	2002/03/06 11:35
-	1464	"micro bubble" or microbubbles	USPAT;	2002/03/06 11:47
-	0	438/506.ccls. and ("micro bubble" or microbubbles)	US-PGPUB	2002/03/06 11:36
-	5648	implant\$ with wafer	USPAT;	2002/03/06 11:36
-	9	438/506.ccls. and (implant\$ with wafer)	US-PGPUB	2002/03/06 11:37
-	203	438/514.ccls.	USPAT;	2002/03/06 11:38
-	0	delaminat\$ and ((bond or bonding or bonded) and 438/514.ccls.)	US-PGPUB	2002/03/06 11:38
-	30	(bond or bonding or bonded) and 438/514.ccls.	USPAT;	2002/03/06 11:40
-	112	438/for.365.ccls.	US-PGPUB	2002/03/06 11:40
-	553582	bond or bonding or bonded	EPO; JPO;	2002/03/06 11:40
-	8984	delaminat\$	DERWENT	2002/03/06 11:41
-	0	delaminat\$ and (438/for.365.ccls. and (bond or bonding or bonded))	EPO; JPO;	2002/03/06 11:41
-	40	438/for.365.ccls. and (bond or bonding or bonded)	DERWENT	2002/03/06 11:42
-	0	438/for.365.ccls. and delaminat\$	EPO; JPO;	2002/03/06 11:43
-	368	438/for.386.ccls.	DERWENT	2002/03/06 11:43
-	0	delaminat\$ and ((bond or bonding or bonded) and 438/for.386.ccls.)	EPO; JPO;	2002/03/06 11:43
-	0	delaminat\$ and 438/for.386.ccls.	DERWENT	2002/03/06 11:43
-	51	(bond or bonding or bonded) and 438/for.386.ccls.	EPO; JPO;	2002/03/06 11:44
-	135	438/for.403.ccls.	DERWENT	2002/03/06 11:45
-	9	(bond or bonding or bonded) and 438/for.403.ccls.	EPO; JPO;	2002/03/06 11:46
-	141	438/for.408.ccls.	DERWENT	2002/03/06 11:46

-	0	delaminat\$ and 438/for.408.ccls.	EPO; JPO;	2002/03/06
-	6	(bond or bonding or bonded) and 438/for.408.ccls.	DERWENT	11:46
-	1912	(bond or bonding or bonded) and delaminat\$	EPO; JPO;	2002/03/06
-	901	"micro bubble" or microbubbles	DERWENT	11:47
-	1	((bond or bonding or bonded) and delaminat\$) and ("micro bubble" or microbubbles)	EPO; JPO;	2002/03/06
-	6085	SOI	DERWENT	11:48
-	6	((bond or bonding or bonded) and delaminat\$) and SOI	EPO; JPO;	2002/03/06
-	5779	SOI	DERWENT	11:48
-	62	(bond or bonding or bonded) and delaminat\$ and SOI	USPAT;	2002/03/06
-	8984	delaminat\$	US-PGPUB	11:52
-	553582	bond or bonding or bonded	USPAT;	2002/03/07
-	17	"smart cut"	US-PGPUB	14:35
-	389	438/for.158.ccls.	EPO; JPO;	2002/03/07
-	111	438/for.485.ccls.	DERWENT	14:38
-	229	438/528.ccls.	EPO; JPO;	2002/03/07
-	440	438/977.ccls.	DERWENT	14:38
-	244	148/dig.12.ccls.	EPO; JPO;	2002/03/07
-	18720	delaminat\$	DERWENT	14:38
-	447475	bond or bonding or bonded	EPO; JPO;	2002/03/07
-	80	"smart cut"	DERWENT	14:38
-	13	148/dig.12.ccls. and delaminat\$ and (bond or bonding or bonded)	EPO; JPO;	2002/03/07
-	2921	batch with furnace	DERWENT	14:36
-	31	delaminat\$ and (batch with furnace)	EPO; JPO;	2002/03/07
-	15	(bond or bonding or bonded) and (delaminat\$ and (batch with furnace))	DERWENT	14:37
			USPAT;	2002/03/07
			US-PGPUB	14:37
			USPAT;	2002/03/07
			US-PGPUB	14:37
			USPAT;	2002/03/07
			US-PGPUB	14:38
			USPAT;	2002/03/07
			US-PGPUB	14:38
			USPAT;	2002/03/07
			US-PGPUB	14:39
			USPAT;	2002/03/07
			US-PGPUB	14:39
			USPAT;	2002/03/07
			US-PGPUB	14:40
			USPAT;	2002/03/07
			US-PGPUB	14:41
			USPAT;	2002/03/07
			US-PGPUB	14:43
			USPAT;	2002/03/07
			US-PGPUB	14:43